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STATEMENT BY APPLICANT

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Application Number	10/780,529
Filing Date	February 17, 2004
First Named Inventor	Jong-Rong Jan
Group Art Unit	2818
Examiner Name	Chuong A. Luu
Attorney Docket Number	9180-30

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Group Art Unit	2818
Examiner Name	Chuong A. Luu

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	10/780,529
(use as many sheets as necessary)				Filing Date	February 17, 2004
Sheet	3	of	7	First Named Inventor	Jong-Rong Jan
				Group Art Unit	2818
				Examiner Name	Chuong A. Luu
				Attorney Docket Number	9180-30

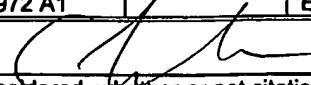
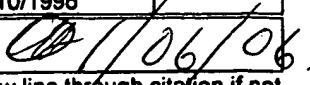
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Examiner Signature	<i>Chu</i>	Date Considered	<i>01/06/2006</i>
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				First Named Inventor	Jong-Rong Jan
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Examiner Signature	<i>CAF</i>	Date Considered	<i>01/06/2006</i>
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute form 1449A/PTO				<i>Complete if Known</i>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				Application Number	10/780,529
				Filing Date	February 17, 2004
				First Named Inventor	Jong-Rong Jan
				Group Art Unit	2818
				Examiner Name	Chuong A. Luu
Sheet	7	of	7	Attorney Docket Number	9180-30

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	268.	Yung et al; <i>Electroplated Solder Joints for Flip-Chip Applications</i> , Transactions on Components, Hybrids, and Manufacturing Technology, vol. 14 No. 3, Sep. 1991, pp 549-559.	
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